

Tpreg™ 1KA Circuit Boards Materials

Tpreg™ 1KA is a thermally conductive electrically insulating pre-preg.

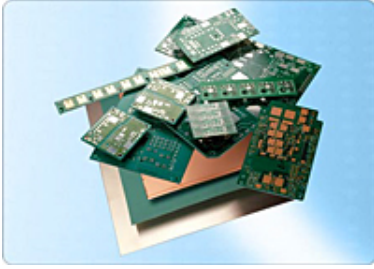
[Stock Locator](#)

The Tlam thermally conductive printed circuit boards use Tpreg™ 1KA dielectric sheets in conjunction with copper foil and an integral metal base plate to provide a circuit board laminate that has superior thermal management capabilities compared to conventional FR4-based printed circuit boards (PCBs). Free-standing Tpreg™ 1KA dielectric sheets facilitate multi-layer and FR4-hybrid PCB construction.

Results 1 - 5 of 5

Item #	Continuous Operating Voltage	Thermal Conductivity	Thermal Resistance	Dielectric Thickness	Peel Strength
1KA04	50 VAC 95 VDC	3.00 W/m-K	0.050 °C-in ² /W 0.350 °C-cm ² /W	0.004 inches 0.102 mm	4.5 lb/in 0.80 kg/cm
1KA06	120 VAC 225 VDC	3.00 W/m-K	0.081 °C-in ² /W 0.552 °C-cm ² /W	0.006 inches 0.152 mm	4.5 lb/in 0.80 kg/cm
1KA08	240 VAC 450 VDC	3.00 W/m-K	0.109 °C-in ² /W 0.703 °C-cm ² /W	0.008 inches 0.203 mm	5.0 lb/in 1.00 kg/cm
1KA10	360 VAC 630 VDC	3.00 W/m-K	0.140 °C-in ² /W 0.880 °C-cm ² /W	0.010 inches 0.245 mm	6.0 lb/in 1.20 kg/cm
1KA12	480 VAC 950 VDC	3.00 W/m-K	0.163 °C-in ² /W 1.050 °C-cm ² /W	0.012 inches 0.305 mm	6.0 lb/in 1.20 kg/cm

Results 1 - 5 of 5



Tpreg™ HTD Circuit Boards Materials

Tpreg™ HTD is a thermally conductive dielectric adhesive pre-preg material.

[Stock Locator](#)

Tpreg™ HTD is used in conjunction with copper foil and an integral metal plate to provide a circuit board laminate that has superior thermal management capabilities and a 150°C continuous use temperature.

Results 1 - 2 of 2

Item #	Max. Continuous Operating Voltage	Thermal Conductivity	Thermal Resistance	Dielectric Thickness	Peel Strength
HTD04	240 VAC 450 VDC	2.20 W/m-K	0.072 °C-in ² /W 0.464 °C-cm ² /W	0.004 inches 0.102 mm	6.5 lb/in 1.16 kg/cm
HTD06	480 VAC 950 VDC	2.20 W/m-K	0.107 °C-in ² /W 0.690 °C-cm ² /W	0.006 inches 0.152 mm	7.0 lb/in 1.25 kg/cm

Results 1 - 2 of 2